

DuPont™ Pyralux® TA & TAH

All-Polyimide Double-Sided Copper-Clad Laminate

Flexible Circuit Materials

Product Description

DuPont™ Pyralux® TA and TAH are Double-sided Copper-clad Laminates featuring adhesive-less, all-polyimide dielectric layers. These materials exhibit excellent low loss performance, enabling remarkable signal integrity in high-speed digital and high-frequency circuit applications. Offered in a variety of both dielectric and conductor thickness, DuPont™ Pyralux® TA and TAH provide designers, fabricators, and assemblers a versatile option for a wide variety of flexible circuit constructions.

Key Features and Benefits

- Low loss dielectric and ED Cu foil (TA) or RA Cu foil (TAH) conductor layers
- Excellent thermal resistance from all-polyimide dielectric
- Minimal variance in dielectric thickness for consistent performance
- High flex and bending reliability due to excellent adhesion between dielectric and copper foil
- UL 94V-0, UL File E161336
- · RoHS Compliant

Packaging

DuPont[™] Pyralux® TA and TAH Double-side Clads are supplied as 100 linear meter (328 ft) rolls in widths of either 250 mm (9.8 in), 260 mm (10.2 in), or 500 mm (19.7 in).

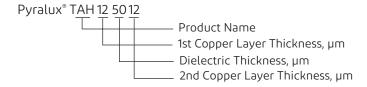
Storage and Warranty

DuPont™ Pyralux® TA and TAH Double-side Clads should be stored in original packaging at temperatures of 4 - 29 °C (40 - 85 °F) and below 70% relative humidity. The product should not be frozen and should be kept dry, clean, and well-protected. Subject to compliance with the foregoing handling and storage recommendations, DuPont's warranties shall remain in effect for the period provided in the DuPont Standard Conditions of Sale.

Table 1 - Standard Pyralux® TA & TAH Clad Offerings

| Product Code | Copper Thickness µm (oz/ft²) & Type | Dielectric Thickness µm (mil) |
|--------------|--|----------------------------------|
| TA122512 | 12 (0.33) ED | 25 (1.0) |
| TA123812 | 12 (0.33) ED | 38 (1.5) |
| TA125012 | 12 (0.33) ED | 50 (2.0) |
| TA182518 | 18 (0.5) ED | 25 (1.0) |
| TA185018 | 18 (0.5) ED | 50 (2.0) |
| TAH125012 | 12 (0.33) RA | 50 (2.0) |

Product Code Key



Processing

DuPont™ Pyralux® TA and TAH Double-side Clads are fully compatible with all conventional flexible circuit fabrication processes, including oxide treatment and wet chemical plated-through-hole de-smearing. Fabricated circuits can be cover coated and laminated together to form multilayers or bonded to heat sinks using polyimide, acrylic, or epoxy adhesives. Pyralux® TA & TAH processing guide available from your DuPont sales representative.

Safe Handling

Prior to handling, DuPont recommends referencing the Pyralux® Safe Handling Guide available at pyralux.dupont.com.

Quality and Traceability

DuPont™ Pyralux® TA and TAH Double-side Clads are manufactured under a certified ISO9001:2015 Quality Management System facility. Complete material and manufacturing records, which include archive samples of finished product, are maintained by DuPont. Each manufactured lot is identified for reference traceability. The packaging label serves as the primary tracking mechanism in the event of customer inquiry and includes the product name, batch number, size, and quantity.

DuPont™ Pyralux® TA & TAH

All-Polyimide Double-Sided Copper-Clad Laminate

Flexible Circuit Materials

Product Performance

Table 2 - DuPont™ Pyralux® TA & TAH Double-sided Copper-clad Laminate Properties

| Property | TA125012 Typical Value | TAH125012B Typical Value | Test Method |
|---|--------------------------------|--------------------------------|---|
| Dielectric Constant (Dk), 10 GHz | 3.2 | 3.2 | ASTM D2520 |
| Loss Tangent (Df), 10 GHz | 0.003 | 0.003 | ASTM D2520 |
| Peel Strength (Adhesion to Copper) As Received, N/mm (lb/in) After Solder, N/mm (lb/in) | > 0.9 (> 5.1) > 0.9 (> 5.1) | > 0.8 (> 4.6) > 0.8 (> 4.6) | IPC-TM-650 2.4.9 |
| Dimensional Stability (MD/TD) After Etching, % After Thermal (200 °C for 30 min), % | ± 0.1 % ± 0.1 % | ± 0.1 % ± 0.1 % | IPC-TM-650 2.2.4 |
| Coefficient of Thermal Expansion XY-Axis, ppm/°C | 25 | 25 | IPC-TM-650 2.4.41 |
| Solder Float, 288 °C for 10 s | Pass | Pass | IPC-TM-650 2.4.13 |
| Moisture Absorption, % | 0.5 | 0.5 | IPC-TM-650 2.6.2 |
| Volume Resistivity, Ω · cm | > 1016 | > 10 ¹⁶ | IPC-TM-650 2.5.17 |
| Surface Resistance, Ω | > 1015 | > 1015 | IPC-TM-650 2.5.17 |
| Tensile Modulus, GPa | > 7 | > 7 | IPC-TM-650 2.4.19 |
| Tensile Strength, MPa | > 350 | > 350 | IPC-TM-650 2.4.19 |
| Elongation, % | 45 | 45 | IPC-TM-650 2.4.19 |
| Flexural Endurance, cycles | > 200 | > 300 | JIS C6471 (MIT) |
| Glass Transition Temperature (Tg), °C | 220 | 200 | DuPont Method, TMA |
| Chemical Resistance Tensile Strength Retention, % Elongation Retention, % Peel Strength Retention, % | > 80% > 80% > 90% | > 80% > 80% > 90% | DuPont Method, NaOH & HCl Dip for 10 min separately |

Data within this table are typical values for the listed product. Performance can vary depending on construction and processing.



pyralux.dupont.com

For more information on Pyralux® TA & TAH Double-side Clads or other DuPont products, please visit our website.

The information provided in this data sheet corresponds to our knowledge on the subject at the date of its publication. It may be subject to revision as new knowledge and experience becomes available. This information is not intended to substitute for any testing you may need to conduct to determine for yourself the suitability of our products for your particular purposes. Since we cannot anticipate all variations in end-use and disposal conditions, DuPont makes no warranties and assumes no liability in connection with any use of this information. It is intended for use by persons having technical skill, at their own discretion and risk. Nothing in this publication is to be considered as a license to operate under or a recommendation to infringe any patent right.

CAUTION: Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see "DuPont Medical Caution Statement," H-50102-5 and "DuPont Policy Regarding Medical Applications" H-50103-5...

DuPont[™], the DuPont Oval Logo, and all products, unless otherwise noted, denoted with [™], [™] or [®] are trademarks, service marks or registered trademarks of affiliates of DuPont de Nemours, Inc. Copyright © 2020 DuPont de Nemours Inc. All rights reserved.

EI-10108 (4/20)